Global Communication Semiconductors, LLC
Corporate & Foundry
23155 Kashiwa Court, Torrance, CA. 90505
Telephone: 310-530-7274 Fax: 310-517-8200
Website: www.gcsincorp.com

Engineering Technician

Job Req: #0718
Department: RF and Power Technology
Status: Full-Time/Hourly
Shift: Day

Job Description

- The main purpose of this role is to perform tests required for wafer processing by execution of the documented processes and procedures in the fab for InP and GaAs HBTs, GaAs and GaN HEMT and BAW filter process development and improvement.
- The process modules may be both wafer front side and backside and may include photolithography, wet etch, dry etch, thin film deposition, photoresist strip, metal lift-off etc.
- Verifies conformance to design and quality standards, identifying those items that are below standard.
- Prepares visual rejection forms for all items that do not meet specifications, and maintains other required documentation.
- Notifies supervisor of significant quality problems and may suggest corrective action.

Job Requirements

- Experience in Semiconductor manufacturing with at least 3 years is required. The candidate should have good experience in some of these process modules such as photolithography, wet/dry etch, lift-off or backside process. The person must be self-motivated as this job will heavily involve processing photolithography, microscope inspection, SEM inspection, wet/dry etch, lift-off and backside process.
- Requires some experience in Excel, Word and PowerPoint. Able to perform mathematical calculations such as Averages & Etch Rate calculations.
- Willing to work overtime, or adapt hours if a special job or schedule requires it.
- Ability to multi-task.